



| <b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-70-6</b> |                    |                       |                   |                    |                        |
|---|--------------------|-----------------------|-------------------|--------------------|------------------------|
| <b>STRESS</b>   | <b>SAMPLE SIZE</b> | <b>DEVICE HR./CYC</b> | <b>CONDITION</b>  | <b>TOTAL FAILS</b> | <b>FAIL PERCENTAGE</b> |
| BOND INT  | 200                | 80,000                | 200 °C + N2       | 0                  | 0.00                   |
| HAST  | 1,634              | 160,650               | 130 °C, 85 % RH   | 0                  | 0.00                   |
| Pressure Pot  | 2,475              | 237,600               | 121°, 15 PSIG     | 0                  | 0.00                   |
| Solder Dunk   | 830                | 2,490                 | 260 °C, 10 s      | 0                  | 0.00                   |
| Solderability   | 485                | 5,430                 | 883 M2003         | 0                  | 0.00                   |
| Temp. Cycle   | 2,474              | 1,601,260             | - 65 °C to 150 °C | 0                  | 0.00                   |